INFORMATION DISCLOSURE CITATION *(Use several sheets if necessary)*	ATTY DOCKET NO. 200-0658	SERIAL NO. 09/804,869
	Applicants: Dan X. Tang	
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FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	NO

OTHER DOCUMENTS   *(Including Author, Title, Date, Pertinent Pages, Etc.)*

M.S.			Lafon, "Solid Modeling With Constraints and Parameterised Features", IEEE, July 1998. Jinsong et al., "Parametric Design with Intelligence Configuration Analysis Mechanism", IEEE, November 1993.
M.S.			Mateos et al., "Parametric and Associative Design of Cartridges for Special Tools", IEEE 1995.

EXAMINER	DATE CONSIDERED 9/22/04

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Examiner Initial	Document No.	Date	Name	Class	Sub-Class	Filing Date
M.S.	5 0 7 0 5 3 4	12/3/91	Lascelles et al.			
m.s.	5 1 1 1 4 1 3	5/5/92	Lazsansky et al.			
M.S.	5 1 9 7 1 2 0	3/23/93	Saxton et al.			

FOREIGN PATENT DOCUMENTS

	Document No.	Date	Country	Class	Sub-Class	Transl. Yes	No

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